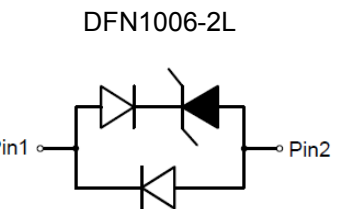
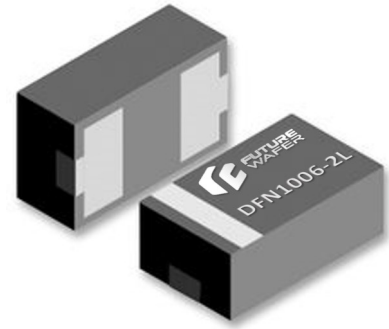


Uni-directional, Extra Low Capacitance ESD Protection

Applications

- Lan equipment
- Video
- DVI
- High Speed Data Line
- Ethernet
- USB 2.0 Power and Data line Protection



Feature

- With TVS Diode
- ESD Protection:Level 4
- Low Capacitance:Cj=0.8pf(max)
- 100 Watts peak pulse power per line(tp=8/20uS)
- Protection one line I/O port

IEC Compatibility

- EN61000-4
- 61000-4-2(ESD):Level 4,Contact:±16kv(MAX)
- 61000-4-4(EFT):40A-5/50ns
- 61000-4-5(Surge):4A-8/20us

Mechanical Characteristics

- Molded JEDEC DFN1006 package
- Packing:Tape and Reel
- Flammability rating UL 94V-0
- Halogen Free

Device Characteristics

Maximum Ratings@25 unless otherwise specified			
Parameter	Symbol	Value	Units
Peak pulse power (tp=8/20us)	PPP	100	Watts
Operating Temperature	TJ	-55~150	°C
Storage Temperature	TSTG	-55~150	°C

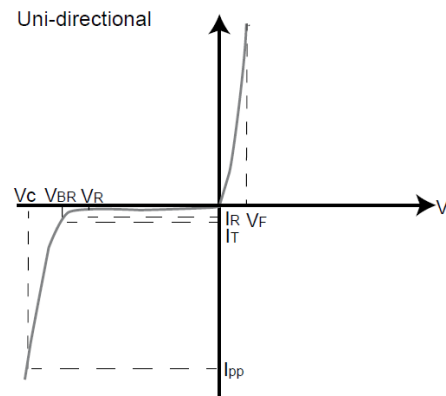
Uni-directional, Extra Low Capacitance ESD Protection

Electrical Characteristics

Parameter	Symbol	Condition	min	Typ.	max	Units
Reverse Stand-off Voltage	V_{RWM}	Pin 2 to 1			5	V
Reverse Breakdown Voltage	V_{BR}	$I_Z=1mA$ Pin2 to 1	6.3		9.5	V
Reverse Leakage Current	$I_R(max)$	@ V_{RWM}			0.1	μA
Forward Voltage	$V_F(max)$	$I_F=15mA$			1.15	V
Clamping Voltage	V_C	$I_{PP}=1A$ $t_p=8/20\mu s$ $I_{PP}=4A$ $t_p=8/20\mu s$			15 20	V
Peak Pulse Current	I_{PP}	$t_p=8/20\mu s$			4	A
Junction Capacitance	$C_{I/O}$	Pin capacitance to GND. $V_{dc}=0V, f=1MHz$			0.8	pf

Electrical Characteristics $T=(25^\circ C)$

Symbol	Parameter
V_{RWM}	Nominal Reverse Working Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Reverse Breakdown Voltage @ I_T
I_T	Test Current for Reverse Breakdown
V_C	Clamping Voltage @ I_{PP}
I_{PP}	Maximum Peak Pulse Current
C_{ESD}	Parasitic Capacitance
V_R	Reverse Voltage
f	Small Signal Frequency



Rating and characteristic curve

FIGURE 1
Non-repetitive Peak pulse power V.S pulse time

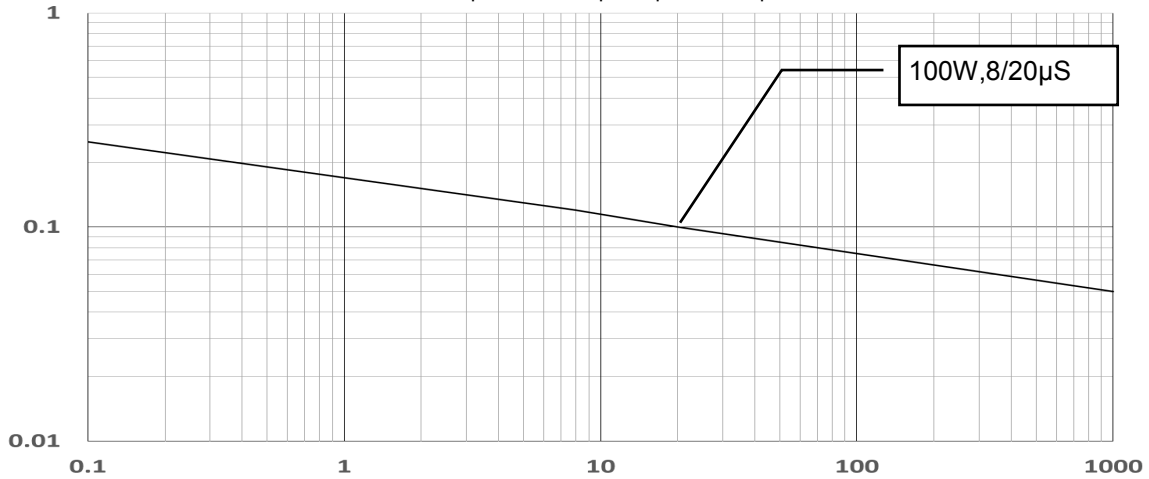


FIGURE 2
Power Derating Curve

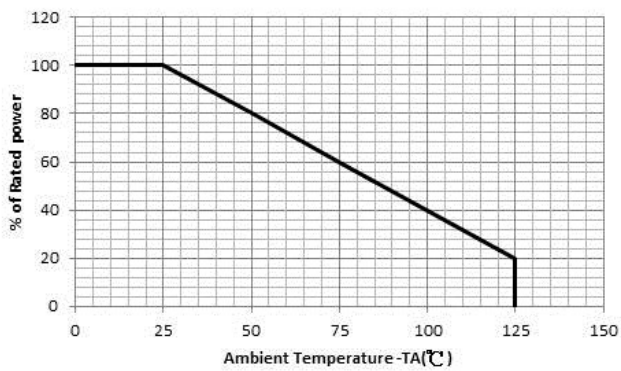
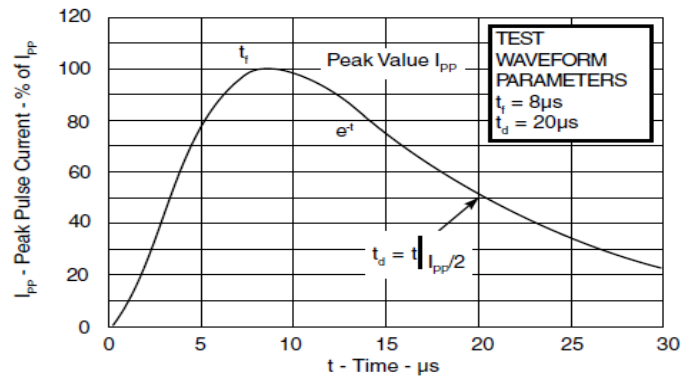
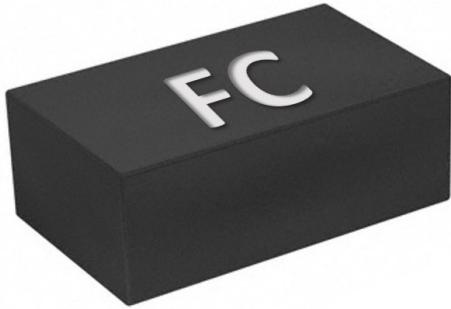


FIGURE 3
Pulse Wave Form



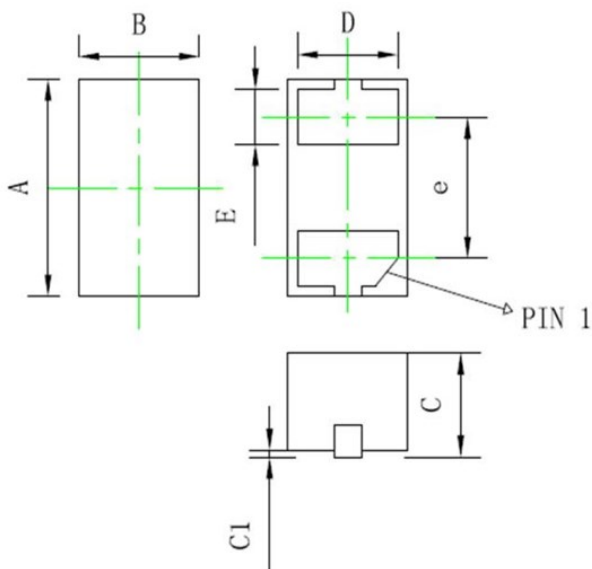
Ordering information

Marking codes



Part No.	Marking
FESD05LCD	FC
Quantity	10,000pcs

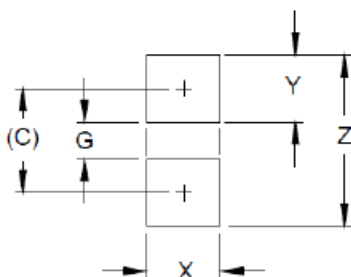
Package information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.95	1.00	1.05
B	0.55	0.60	0.65
C	0.40	0.45	0.50
C1			0.05
D	0.45	0.50	0.55
e	0.65 BSC		
E	0.20	0.25	0.30

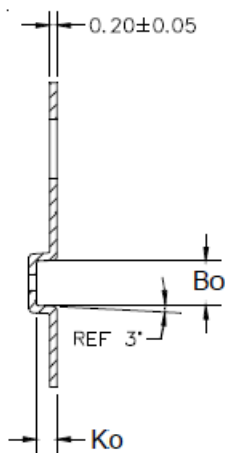
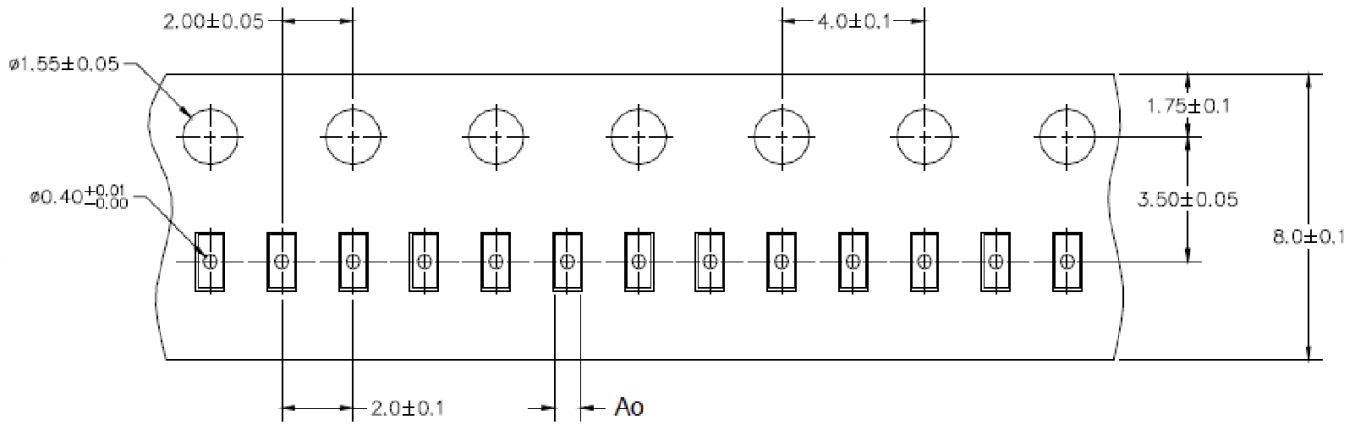
Unit : mm

Pad Layout



DIMENSIONS		
DIM	INCHES	MILLIMETERS
C	(.033)	(0.85)
G	.012	0.30
X	.024	0.60
Y	.022	0.55
Z	.055	1.40

Tape & Reel information



A0	B0	K0
0.69 +/-0.10 mm	1.19 +/-0.10 mm	0.66 +/-0.10 mm



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